Amendments to the Specification:

Please replace the paragraph beginning on page 31, line 4 with the following rewritten paragraph:

Inspection may also be performed periodically after the reticle has been released for semiconductor fabrication to determine if the reticle no longer meets qualification standards. For example, the reticle may be damaged after release by accumulation of particles or other material on the reticle, pellicle damage, and damage caused by electrostatic discharge. Such damage may be sufficient to cause the reticle to fail to meet qualification standards. Example of systems and methods for inspecting a reticle subsequent to qualification are illustrated in U.S. Patent Application Serial No. 08/993,107 entitled "Method for Inspecting a Reticle," to Bareket et al., now U.S. Patent No. 6,614,520, which is incorporated by reference as if fully set forth herein. The systems and methods described herein may be further configured and may include additional steps, respectively, as illustrated and described by Bareket et al.